

CLAIMS:

1. A method of manufacturing an electronic device comprising a substrate with a metallization side, on which metallization an electrical element is present in a cavity that is bounded by the substrate and a cover, the method comprising the steps of:

- providing a foil;
- 5 - applying the foil to the metallization side of the substrate while forming the cavity, part of the foil forming the cover; and
- affixing the cover to the substrate,

characterized in that

- a foil is provided which comprises a patterned layer on the first side and a sacrifice layer on the second side,
 - the foil is placed to a protruding part of the substrate, an interstice between the substrate and the foil developing around the cavity; and
 - the foil is affixed to the substrate by filling an interstice around the substrate with isolating material.

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2. A method as claimed in claim 1, characterized in that a patterned sub-layer is present in the carrier between the patterned layer and the sacrifice layer, which patterned layer and sub-layer have a first and a second pattern which are mutually distinguished by a recess that has a larger diameter in the plane of the sub-layer than in the plane of the 20 patterned layer thanks to which carrier the patterned layer is embedded in the isolating material when the isolating material is applied.

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3. A method as claimed in claim 1, characterized in that the sacrifice layer is removed after the foil has been affixed to the substrate.

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4. A method as claimed in claim 1, characterized in that the patterned layer contains a metal.

5. A method as claimed in claim 4, characterized in that guiding tracks are present on the metallization side of the substrate beside the cavity, on which tracks electroconductive connectors are mounted prior to the mounting of the carrier, which connectors are brought into contact with tracks in the patterned layer when the carrier is

5 mounted.

6. A method as claimed in claim 5, characterized in that the tracks in the patterned layer which are brought into contact with electrical connectors, are contact pads on which solder can be deposited.

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7. A method as claimed in claim 1, characterized in that:

- a deformed foil is used as a foil, which deformed foil has a protrusion that is bounded by an edge; and

- the foil is affixed to the substrate so that the protrusion in the foil forms the cover of the cavity and the edge is in contact with the substrate.

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8. An electronic device comprising a substrate with a metallization side on which metallization side an electrical element is present in a cavity that is bounded by the substrate and a cover, characterized in that as a cover a layer is present which is stuck to the substrate 20 by isolating material that is situated in a space beside the cavity, the layer being mechanically embedded in the isolating material.

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9. An electronic device as claimed in claim 8, characterized in that the mechanically embedded layer contains a metal.

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An electronic device as claimed in claim 8, characterized in that the substrate comprises an integrated circuit.

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11. An electronic device as claimed in claim 8 and method as claimed in claim 1, characterized in that the electrical element is a micro-mechanical system (MEMS) element.